

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Jeong-sic JEON, et al.

Serial No. 10/003,412

Filed: December 6, 2001

For: APPARATUS FOR MANUFACTURING
SEMICONDUCTOR DEVICE



Notice of Allowance Mailed:
March 25, 2004

Art Unit: 1763

Examiner: Parviz HASSANZADEH

Confirmation No. 5396

*O.K. to
enter
p.t.
7/29/04*

AMENDMENT UNDER 37 C.F.R. § 1.312

Mail Stop: ISSUE FEE
Commissioner for Patents
United States Patent and Trademark Office
Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENT

It is respectfully requested that the above-referenced application be returned to the Examiner for consideration and entry of the following amendment:

IN THE SPECIFICATION

Kindly amend the specification as follows:

Page 13, paragraph [0035]

[0035] For a wafer 30 shown in Fig. 1A having a diameter identical to the diameter M3 of the wafer 130 shown in Fig. 2, the diameter M1 of the insulating plate 120 shown in Fig. 2 would preferably be larger than the diameter L1 of an insulating plate 20 in Fig. **1A** 2. Thus, the distance spanned by the plurality of induction coils 114 shown in Fig. 2 would be greater than distance spanned by the plurality of induction coils 14 shown in Fig. 1A.